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# ZLLS410

## 10V Low leakage Schottky diode in SOD323

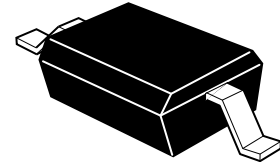
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### Summary

$V_R > 10V$ ;  $I_F = 570mA$ ;  $I_R$  typ.  $2\mu A$

### Description

This compact SOD323 packaged 10 volt Schottky diode offers users an excellent performance combination, comprising high current operation, extremely low leakage and low forward voltage ensuring suitability for low voltage applications requiring efficient operation at higher temperatures above  $85^\circ C$  - see safe operating area charts on page 5.



### Features

- Extremely low leakage
- High current capability
- Low  $V_F$  fast switching Schottky
- SOD323 package
- Package thermally rated to  $150^\circ C$



### Applications

- Low power DC-DC conversion
- Level shifting
- Reverse blocking

### Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZLLS410TA	7	8	3000

### Device marking

41

**Absolute maximum ratings**

Parameter	Symbol	Limit	Unit
Continuous reverse voltage	$V_R$	10	V
Forward current	$I_F$	570	mA
Peak repetitive forward current Rectangular pulse duty cycle 50%, Pulse width = 100 $\mu$ s	$I_{FPK}$	1.25	A
Non repetitive forward current $t \leq 100\mu$ s $t \leq 10$ ms	$I_{FSM}$	17 4	A
Power dissipation at $T_{amb} = 25^\circ\text{C}$			
Continuous	$P_D$	330	mW
$t \leq 5$ secs		390	mW
Operating and storage temperature range	$T_j, T_{stg}$	-55 to 150	$^\circ\text{C}$

**Thermal resistance**

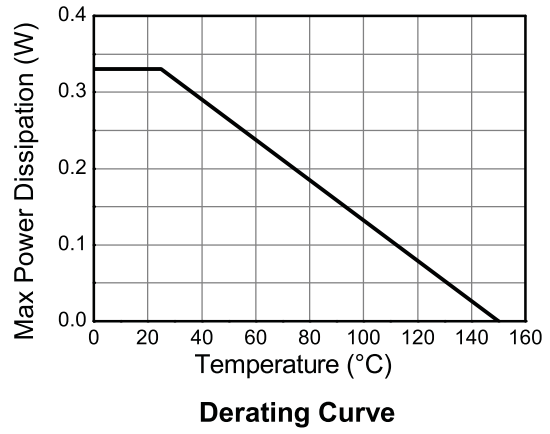
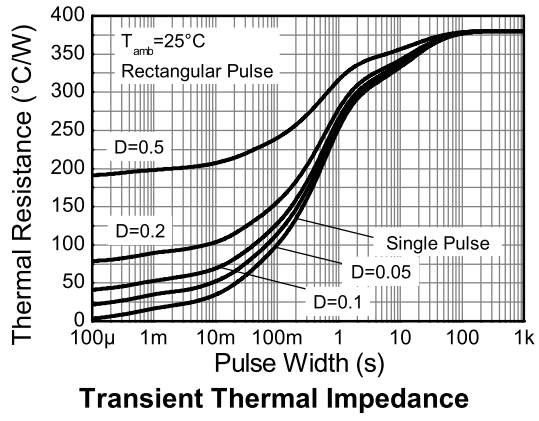
Parameter	Symbol	Limit	Unit
Junction to ambient <sup>(a)</sup>	$R_{\theta JA}$	379	$^\circ\text{C}/\text{W}$
Junction to ambient <sup>(b)</sup>	$R_{\theta JA}$	317	$^\circ\text{C}/\text{W}$

**NOTES:**

(a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

(b) For a device surface mounted on FR4 PCB measured at  $t < 5$  secs.

## Thermal characteristics



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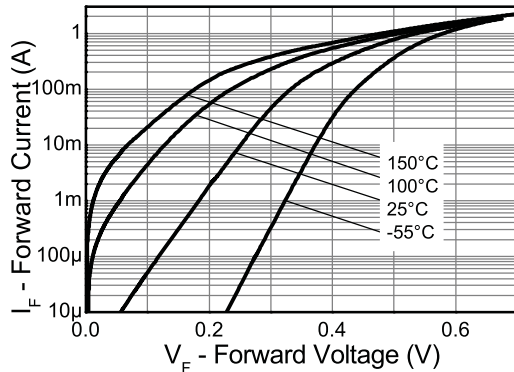
## Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Reverse breakdown voltage	$BV_{(BR)R}$	10			V	$I_R = 200\mu\text{A}$
Forward voltage	$V_F$		250	290	mV	$I_F = 10\text{mA}^{(*)}$
			330	380	mV	$I_F = 100\text{mA}^{(*)}$
			535	580	mV	$I_F = 1\text{A}^{(*)}$
Reverse current	$I_R$		1.8	4	$\mu\text{A}$	$V_R = 5\text{V}$
			2.2	5	$\mu\text{A}$	$V_R = 8\text{V}$
			2.5	6	$\mu\text{A}$	$V_R = 10\text{V}$
				300	$\mu\text{A}$	$V_R = 8\text{V}, T_A = 85^{\circ}\text{C}$
Diode capacitance	$C_D$		26		pF	$f = 1\text{MHz}, V_R = 10\text{V}$
Reverse recovery time	$t_{rr}$		3		ns	Switched from $I_F = 500\text{mA}$ to $V_R = 5.5\text{V}$
Reverse recovery charge	$Q_{rr}$		210		pC	measured @ $I_R 50\text{mA}$ $di/dt = 500\text{mA/ns}$ $R_{source} = 6\Omega < R_{load} = 10\Omega$

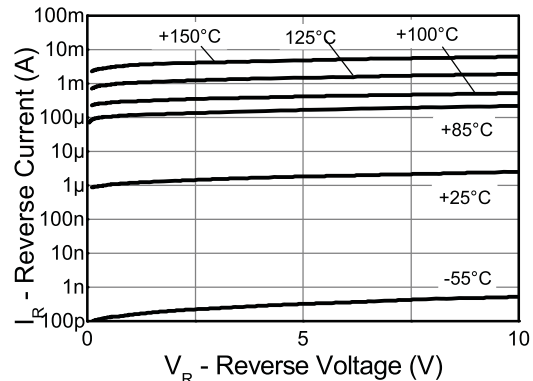
### NOTES:

(\*) Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

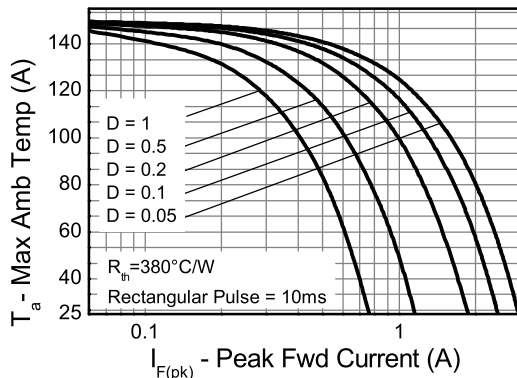
## Typical characteristics



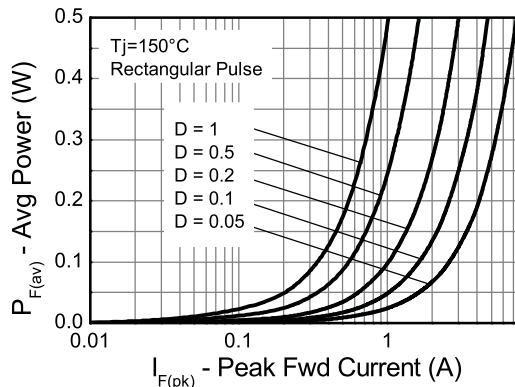
**Typical Forward Characteristics**



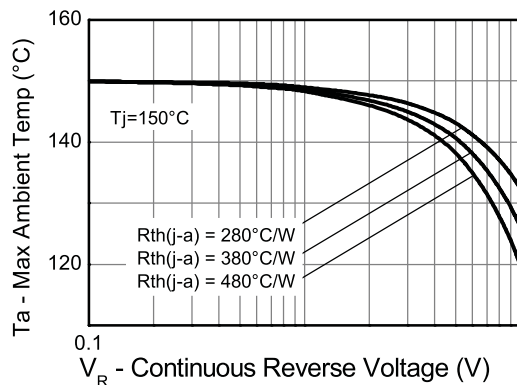
**Typical Reverse Characteristics**



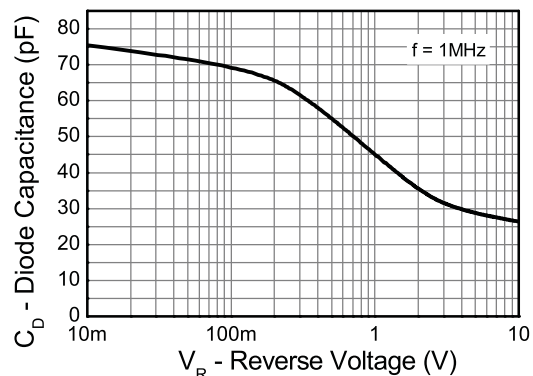
**Typical Forward Safe Operating Area**



**Forward Power vs Peak Current**



**Typical Reverse Safe Operating Area**



**Capacitance vs Reverse Voltage**

### Note:

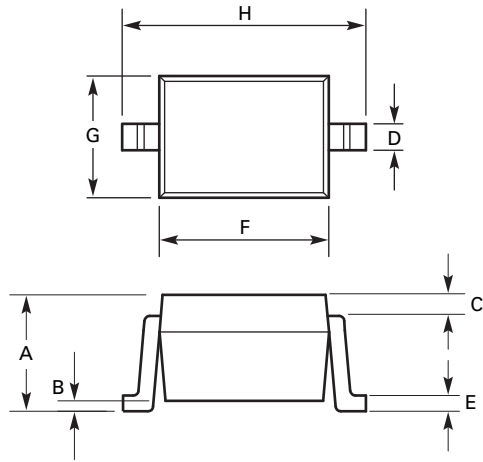
1. Both forward and reverse dissipation contributes to junction temperature rise. Forward and reverse junction temperature rise are determined and added together to give total junction temperature rise.

2. The safe operating curves are typical examples. Thermal resistance, pulse width and duty cycles are dependant on application.

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# ZLLS410

## Package outline - SOD323



## Top mark



Cathode terminal is to RIGHT HAND side of part mark  
Part marking text displayed is for example only

Dim.	Millimeters		Dim.	Millimeters	
	Min.	Max.		Min.	Max.
A	0.91	1.16	E	0.127	0.200
B	0.00	0.10	F	1.52	1.77
C	-	-	G	1.11	1.37
D	0.33	0.40	H	2.46	2.71

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